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Part Number: XZFBBA05C

SURFACE MOUNT DISPLAY

BBA

Features

- 0.2 inch digit height
- Robust package
- Low power consumption
- Standard configuration: Gray face w/ white
- Standard Package: 650pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS compliant

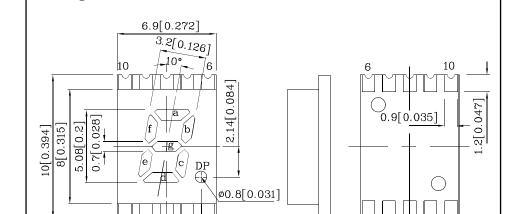






ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



5 1.4<u>4[0.057]</u>

2.4[0.094]

Ø0.6[0.024]

Package Schematics

1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.

[3][0.118]

b

2. Specifications are subject to change without notice.

1.44X4=5.76[0.227]

3. The gap between the reflector and PCB shall not exceed 0.25mm.

Absolute Maximum Ratings (T _A =25°C)	BBA (InGaN)	Unit		
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	100	mA	
Power Dissipation	P_{D}	120	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85	30	
Electrostatic Discharge Thresho (HBM)	1000	V		

Operating Characteristics (T _A =25°C)		BBA (InGaN)	Unit		
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	3.05	V		
Forward Voltage (Max.) (I _F =10mA)	V_{F}	4	V		
Reverse Current (Max.) $(V_R=5V)$	$I_{ m R}$	10	uA		
Wavelength of Peak Emission CIE127-2007* (Typ.) $(I_F=10\text{mA})$	λР	468*	nm		
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	465*	nm		
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$\triangle \lambda$	21	nm		
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	100	pF		
Luminous Intensity Wavelength					

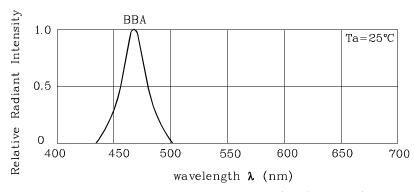
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Part Number	Emitting Color	Emitting Material	CIE127-2007* (I _F =10mA) ucd		CIE127-2007* nm λP	Description
			min.	typ.		
XZFBBA05C	Blue	InGaN	2200*	4290*	468*	Common Cathode, Rt. Hand Decimal.

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Jan 06,2014

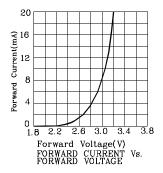


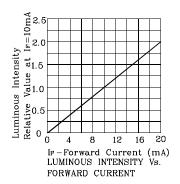


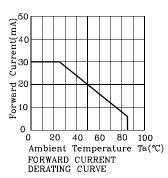


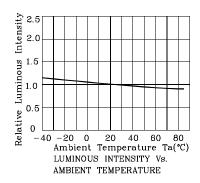
RELATIVE INTENSITY Vs. CIE WAVELENGTH

❖ BBA



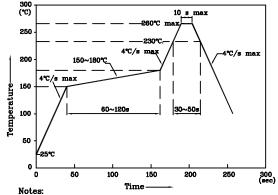






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

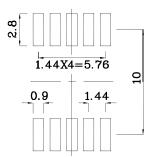


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

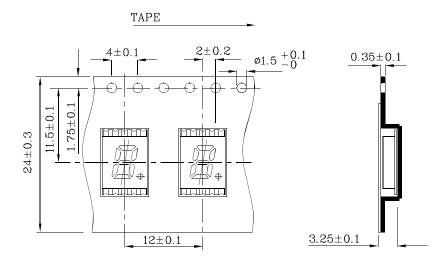




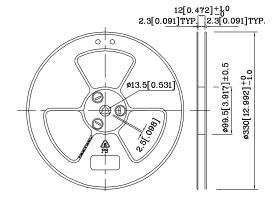
❖ Recommended Soldering Pattern (Units: mm; Tolerance: ±0.15)



❖ Tape Specification (Units:mm)



* Reel Dimension



Remarks:

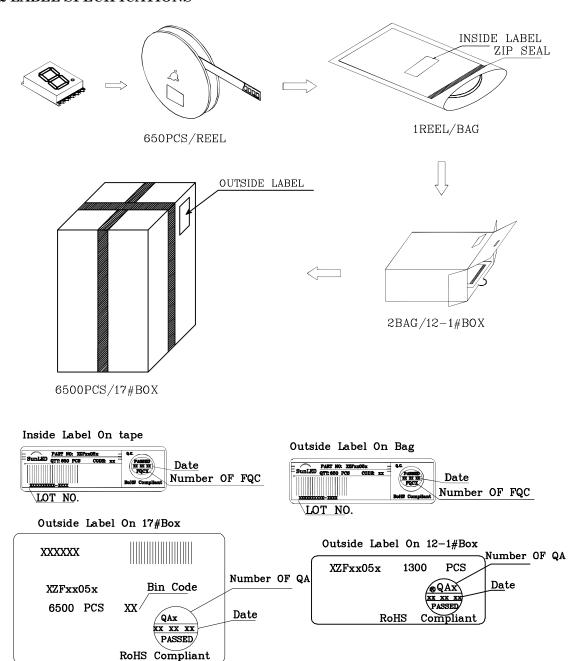
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
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